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## **FQB47P06**

## P-Channel QFET® MOSFET

-60 V, -47 A, 26 mΩ

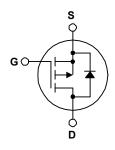
## **Description**

This P-Channel enhancement mode power MOSFET is produced using ON Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

### **Features**

- -47 A, -60 V,  $R_{DS(on)}$  = 26 m $\Omega$  (Max.) @  $V_{GS}$  = .10 V,  $I_D$  = -23.5 A
- Low Gate Charge (Typ. 84 nC)
- Low Crss (Typ. 320 pF)
- 100% Avalanche Tested
- 175°C Maximum Junction Temperature Rating





## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter		FQB47P06TM-AM002	Unit
$V_{DSS}$	Drain-Source Voltage		-60	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C)		-47	Α
	- Continuous (T <sub>C</sub> = 100°C)		-33.2	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	-188	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 25	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	820	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	-47	Α
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	16	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	-7.0	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> = 25°C) *		3.75	W
	Power Dissipation (T <sub>C</sub> = 25°C)		160	W
	- Derate above 25°C		1.06	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +175	°C
T <sub>L</sub>	Maximum lead temperature for soldering, 1/8" from case for 5 seconds		300	°C

### **Thermal Characteristics**

Symbol	Parameter	FQB47P06TM-AM002	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.94	
D	Thermal Resistance, Junction to Ambient (Minimum Pad of 2-oz Copper), Max.	62.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (*1 in <sup>2</sup> Pad of 2-oz Copper), Max.	40	

## **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQB47P06TM-AM002	FQB47P06	D <sup>2</sup> -PAK	Tape and Reel	330 mm	24 mm	800 units

### **Flectrical Characteristics**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-60			V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = -250 μA, Referenced to 25°C		-0.06		V/°C
I <sub>DSS</sub>	Zana Cata Valtana Duain Cumant	V <sub>DS</sub> = -60 V, V <sub>GS</sub> = 0 V			-1	μА
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -48 V, T <sub>C</sub> = 150°C			-10	μА
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = -25 V, V <sub>DS</sub> = 0 V			-100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = 25 V, V <sub>DS</sub> = 0 V			100	nA
On Cha	aracteristics Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-2.0		-4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = -10 V, I <sub>D</sub> = -23.5 A		0.021	0.026	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = -30 V, I <sub>D</sub> = -23.5 A		21		S

$C_{iss}$	Input Capacitance	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$	 2800	3600	pF
Coss	Output Capacitance	f = 1.0 MHz	 1300	1700	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		 320	420	pF

## **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = -30 V, I <sub>D</sub> = -23.5 A,	 50	110	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega$	 450	910	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	1.9	 100	210	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	 195	400	ns
$Q_g$	Total Gate Charge	V <sub>DS</sub> = -48 V, I <sub>D</sub> = -47 A,	 84	110	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = -10 V	 18		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4)	 44		nC

### **Drain-Source Diode Characteristics and Maximum Ratings**

		ia maximam ratingo			
Is	Maximum Continuous Drain-Source Diode Forward Current		 	-47	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current		 	-188	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = -47 A	 	-4.0	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>S</sub> = -47 A,	 130		ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> / dt = 100 A/μs	 0.55		μС

- 1. Repetitive rating : pulse-width limited by maximum junction temperature. 2. L = 0.43 mH, I $_{AS}$  = -47 A, V $_{DD}$  = -25 V, R $_{G}$  = 25  $\Omega$ , starting T $_{J}$  = 25°C. 3. I $_{SD}$   $\leq$  -47 A, di/dt  $\leq$  300 A/ $\mu$ s , V $_{DD}$   $\leq$  BV $_{DSS}$ , starting T $_{J}$  = 25°C. 4. Essentially independent of operating temperature.

## **Typical Characteristics**

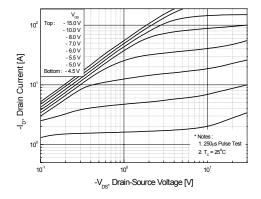


Figure 1. On-Region Characteristics

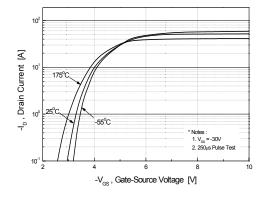


Figure 2. Transfer Characteristics

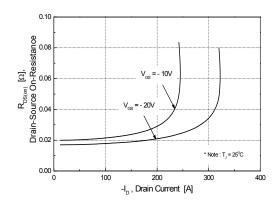


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

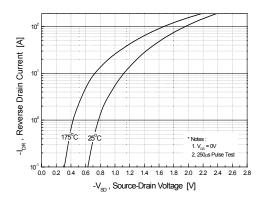
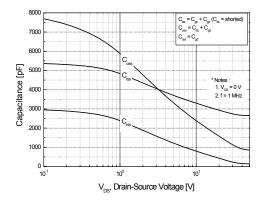
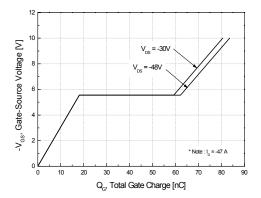


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature





## Typical Characteristics (Continued)

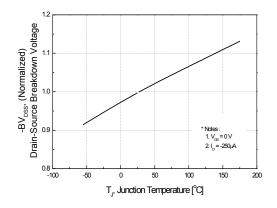
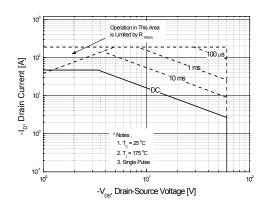


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



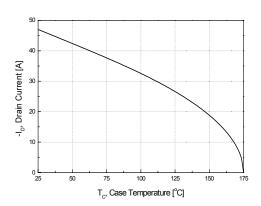


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

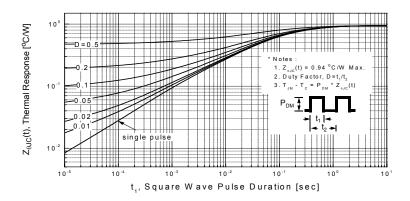


Figure 11. Transient Thermal Response Curve

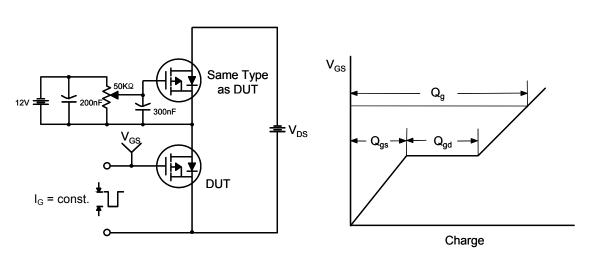


Figure 12. Gate Charge Test Circuit & Waveform

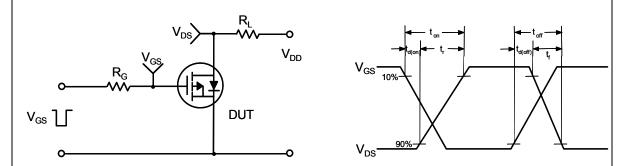


Figure 13. Resistive Switching Test Circuit & Waveforms

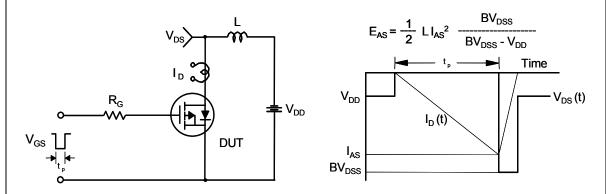
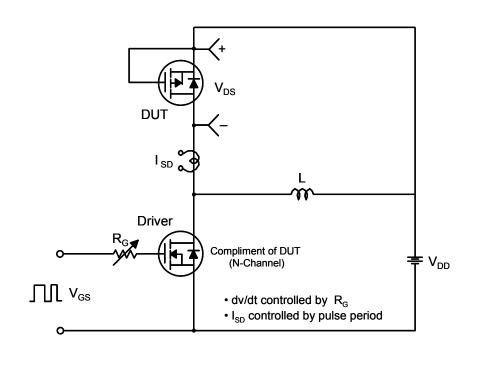


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



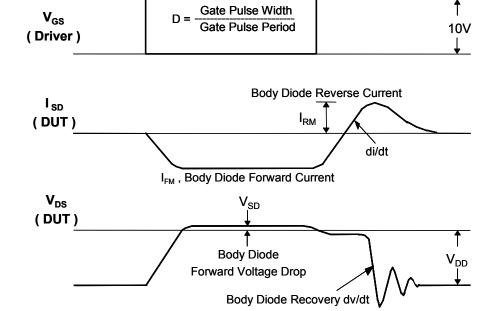


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

### **Mechanical Dimensions**

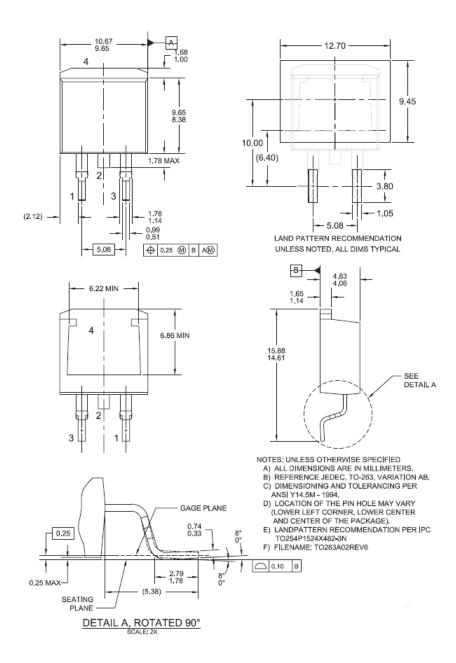


Figure 16. TO263 (D<sup>2</sup>PAK), Molded, 2-Lead, Surface Mount

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